

128-22**PLATEABLE SOLVENT-RESISTANT ELECTRICALLY CONDUCTIVE INK**

DESCRIPTION: 128-22 is a solvent-resistant, stencil-printable, electrically conductive ink and coating. This product features excellent adhesion to Kapton, Mylar, glass, polycarbonate and a variety of other substrates. Unlike conventional conductive materials, this product is very resistant to harsh chemical environments including plating baths and it is also very resistant to scratching and creasing. Some applications for 128-22 include, but are not limited to, EMI/RFI shielding of polyimide flexible circuits, polymer thick film circuitry, membrane switches, electrical attachments for surface mounted devices, and anode coatings for tantalum capacitors. 128-22 is designed to spontaneously nucleate for electroless nickel plating.

TYPICAL CURED PROPERTIES:

Viscosity (10/s @ 25°C, cps)	30,000 – 65,000
Filler	Silver
Percent Silver (cured)	> 85
Crease Resistance	Excellent
Volume Resistance (Ω -cm)	0.00006
Sheet Resistivity (Ω /sq./mil)	0.025
Solderable	No
Hydrolytic Stability	Excellent
Useful Temperature Range (°C)	-55 to +200
Thermal Stability (°C)	Good to +280

SUGGESTED HANDLING & CURING: 128-22 is ready to use as supplied. Further thinning may be accomplished by adding small amounts of CMI thinner 102-03 and/or thinner 113-12. Prior to using, be certain to re-suspend silver. **Best** properties result when using a low temperature pre-cure drying step of 10 – 15 minutes at 110°C followed by curing for 2 hours at 200°C or 90 minutes at 225°C. Curing schedules between 150°C and 225°C can be used for good properties in most applications.

STORAGE: Shelf life: 3 months at 25°C; or 6 months at 5°C; or 12 months at –10 °C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

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